Preferred Device

Dual Schottky Barrier Diodes

Application circuit designs are moving toward the consolidation of device count and into smaller packages. The new SOT-363 package is a solution which simplifies circuit design, reduces device count, and reduces board space by putting two discrete devices in one small six-leaded package. The SOT-363 is ideal for low-power surface mount applications where board space is at a premium, such as portable products.

Surface Mount Comparisons:

	SOT-363	SOT-23
Area (mm ²)	4.6	7.6
Max Package P _D (mW)	120	225
Device Count	2	1

Space Savings:

Package	$1 \times \text{SOT-23}$	$2 \times \text{SOT-23}$	
SOT-363	40%	70%	

The MBD110DW, MBD330DW, and MBD770DW devices are spin-offs of our popular MMBD101LT1, MMBD301LT1, and MMBD701LT1 SOT-23 devices. They are designed for high-efficiency UHF and VHF detector applications. Readily available to many other fast switching RF and digital applications.

Features

- Extremely Low Minority Carrier Lifetime
- Very Low Capacitance
- Low Reverse Leakage
- Pb–Free Packages are Available

MAXIMUM RATINGS

Ratir	Symbol	Value	Unit	
Reverse Voltage	MBD110DWT1 MBD330DWT1 MBD770DWT1	V _R	7.0 30 70	V
Forward Power Dissip	P _F	120	mW	
Junction Temperature		TJ	-55 to +125	°C
Storage Temperature	T _{stg}	-55 to +150	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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Anode 1 •	6 Cathode
N/C 2 0 0	5 N/C
Cathode 3 •	4 Anode



SC-88 / SOT-363 CASE 419B STYLE 6

MARKING DIAGRAM



xx = Device Code Refer to Ordering Table, page 2 M = Date Code

= Pb–Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

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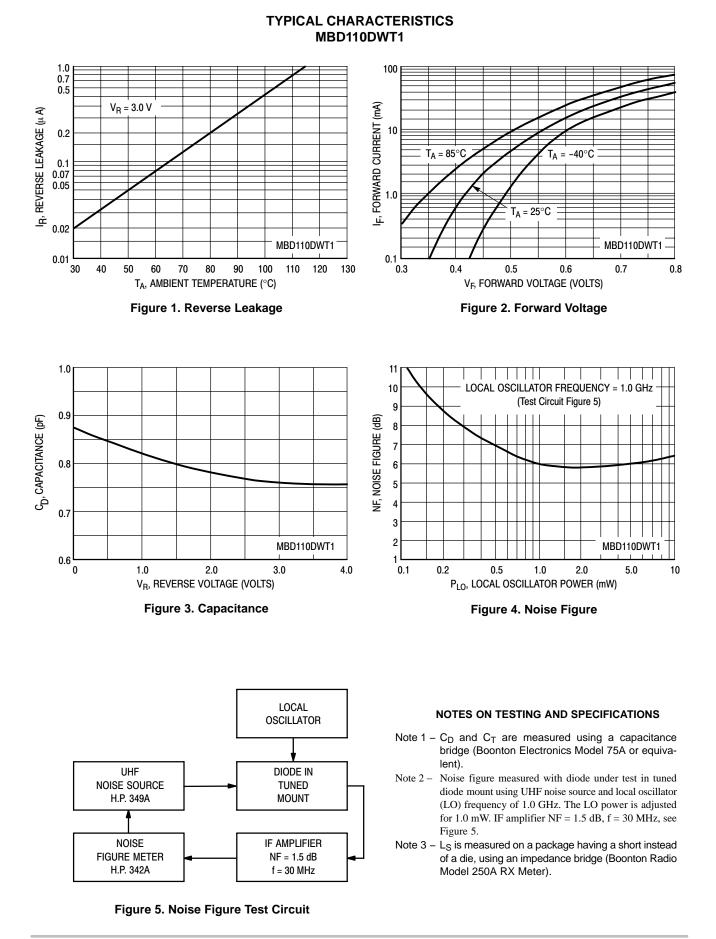
Characteristic		Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μ A)	MBD110DWT1 MBD330DWT1 MBD770DWT1	V _{(BR)R}	7.0 30 70	10 - -	- - -	V
Diode Capacitance $(V_R = 0, f = 1.0 \text{ MHz}, \text{ Note } 1)$	MBD110DWT1	C _D	_	0.88	1.0	pF
Total Capacitance ($V_R = 15$ Volts, f = 1.0 MHz) ($V_R = 20$ Volts, f = 1.0 MHz)	MBD330DWT1 MBD770DWT1	CT		0.9 0.5	1.5 1.0	pF
Reverse Leakage (V _R = 3.0 V) (V _R = 25 V) (V _R = 35 V)	MBD110DWT1 MBD330DWT1 MBD770DWT1	I _R	- - -	0.02 13 9.0	0.25 200 200	μA nA nA
Noise Figure (f = 1.0 GHz, Note 2)	MBD110DWT1	NF	_	6.0	_	dB
Forward Voltage $(I_F = 10 \text{ mA})$ $(I_F = 1.0 \text{ mA})$ $(I_F = 10 \text{ mA})$ $(I_F = 1.0 \text{ mA})$ $(I_F = 1.0 \text{ mA})$	MBD110DWT1 MBD330DWT1 MBD770DWT1	V _F	- - - -	0.5 0.38 0.52 0.42 0.7	0.6 0.45 0.6 0.5 1.0	V

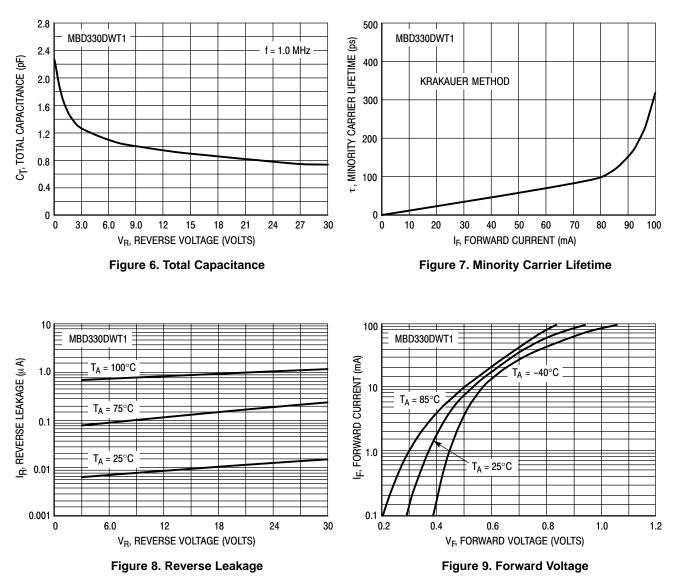
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

ORDERING INFORMATION

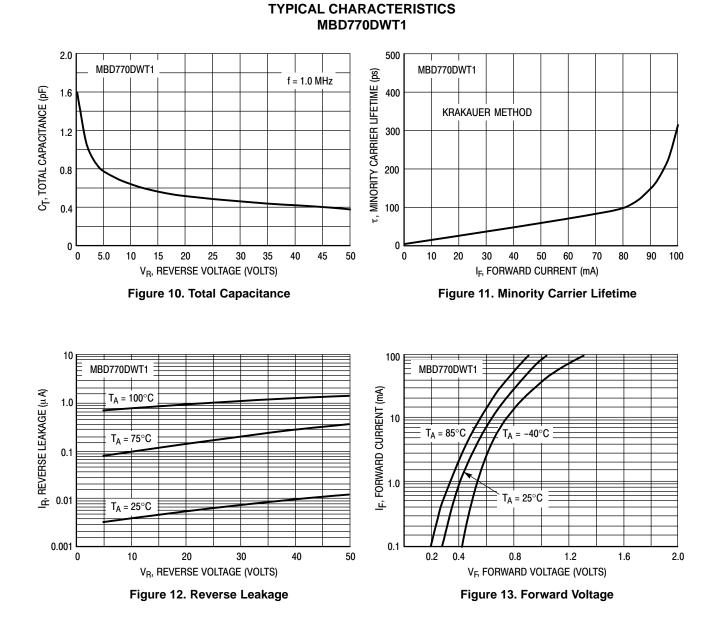
Device	Marking	Package	Shipping [†]
MBD110DWT1		SC-88 / SOT-363	
MBD110DWT1G	M4	SC-88 / SOT-363 (Pb-Free)	
MBD330DWT1		SC-88 / SOT-363	
MBD330DWT1G	T4	T4 SC-88 / SOT-363 (Pb-Free)	
MBD770DWT1		SC-88 / SOT-363	
MBD770DWT1G	H5	SC-88 / SOT-363 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





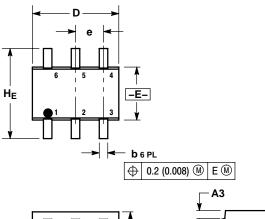
TYPICAL CHARACTERISTICS MBD330DWT1

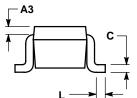


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PACKAGE DIMENSIONS

SC-88 / SC-70 / SOT-363 CASE 419B-02 ISSUE W





NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M 1982

2. CONTROLLING DIMENSION: INCH.

3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.20 REF				0.008 RI	EF
b	0.10	0.21	0.30	0.004	0.008	0.012
С	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
Е	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC			0.026 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	2.00	2.10	2.20	0.078	0.082	0.086

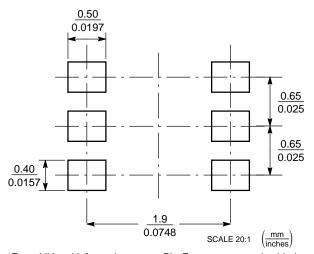
STYLE 6: PIN 1. ANODE 2

N 1. ANODE 2
2. N/C
3. CATHODE 1

4. ANODE 1

5. N/C 6. CATHODE 2

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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